

EAST Search History

EAST Search History (Prior Art)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	8	"6774497"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/19 11:00
L2	2	"6774497".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/19 11:00
S1	5	"2004103928"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/10/28 14:14
S2	2	"20040046252"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/10/28 14:20
S3	4	"2002057186"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/10/28 17:24
S4	2	"2003179100"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/10/28 17:25
S5	3	"2002343829"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/10/28 17:25
S6	2	"2000138255"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/10/28 17:26
S7	1	"10594844"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/10/28 17:38

S8	2	"20040046252"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/10/28 17:43
S9	1	"9172035"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/10/28 17:53
S10	0	"009172035"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/10/28 17:53
S11	2	9-172035	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/10/28 17:54
S12	2	"5088189".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/10/28 18:05
S13	2	"6028011".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/10/28 18:05
S14	107091	wiring near board	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/10/28 18:05
S15	1787	solder near resist near film	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/10/28 18:06
S16	16	S14 near S15	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/10/28 18:06
S17	2	US "20040046252"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/03 10:03
S18	914276	(wiring or circuit or (printed near circuit) or support) near (board or substrate or base) or PCB	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/03 10:28

S19	45462	(flip near chip) or flip-chip	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM. TDB	ADJ	ON	2008/11/03 10:28
S20	56306	(solder near bump\$1) or (solder near ball\$1)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM. TDB	ADJ	ON	2008/11/03 10:29
S21	6292	S18 same (solder near resist)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM. TDB	ADJ	ON	2008/11/03 10:29
S22	13703	S18 and S19 and S20	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM. TDB	ADJ	ON	2008/11/03 10:29
S23	543	S19 and S20 and S21	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM. TDB	ADJ	ON	2008/11/03 10:30
S24	446	S23 and thickness	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM. TDB	ADJ	ON	2008/11/03 10:47
S25	4	"11077930"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM. TDB	ADJ	ON	2008/11/03 11:04
S26	0	("7005585").URPN.	USPAT	ADJ	ON	2008/11/03 11:05
S27	14	"4859808"	USPAT	ADJ	ON	2008/11/03 11:05
S28	1	"4859808".pn.	USPAT	ADJ	ON	2008/11/03 11:30
S29	1	"5218234".pn.	USPAT	ADJ	ON	2008/11/03 11:31
S30	1	"5378859".pn.	USPAT	ADJ	ON	2008/11/03 11:31
S31	1	"5397864".pn.	USPAT	ADJ	ON	2008/11/03 11:32
S32	1	"5650595".pn.	USPAT	ADJ	ON	2008/11/03 11:33

S33	0	S23 and (thickness ner resin)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/03 12:00
S34	49	S23 and (thickness near resin)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/03 12:00
S35	3	S23 and (thickness near underfill)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/03 12:06
S36	111	((thickness near underfill)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/03 12:07
S37	52	S23 and (thickness near solder resist)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/03 12:17
S38	3	"20050155790"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/03 13:29
S39	525	S23 and method	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/03 13:58
S40	125	S39 and pressing	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/03 13:58
S41	0	S39 and (deposit near liquid near resin)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/03 14:36
S42	11	(deposit near liquid near resin)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/03 14:36
S43	54	S39 and (liquid near resin)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/03 14:36

S44	914276	(wiring or circuit or (printed near circuit) or support) near (board or substrate or base) or PCB	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM TDB	ADJ	ON	2008/11/03 18:49
S45	45462	(flip near chip) or flip-chip	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM TDB	ADJ	ON	2008/11/03 18:49
S46	56306	(solder near bump\$1) or (solder near ball\$1)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM TDB	ADJ	ON	2008/11/03 18:49
S47	6292	S44 same (solder near resist)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM TDB	ADJ	ON	2008/11/03 18:49
S48	543	S45 and S46 and S47	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM TDB	ADJ	ON	2008/11/03 18:49
S49	525	S48 and method	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM TDB	ADJ	ON	2008/11/03 18:49
S50	54	S49 and (liquid near resin)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM TDB	ADJ	ON	2008/11/03 18:49
S51	20	S50 and plasma	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM TDB	ADJ	ON	2008/11/03 18:49
S52	117	S49 and plasma	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM TDB	ADJ	ON	2008/11/03 18:52
S53	0	"2005/0155790"),URPN.	USPAT	ADJ	ON	2008/11/03 19:42
S54	0	"2002256288"	USPAT	ADJ	ON	2008/11/03 19:42
S55	1	"2002-256288"	USPAT	ADJ	ON	2008/11/03 19:42

S61	159323	bump or ball SAME (air bubble)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/04/28 13:35
S62	1407322	aperture	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/04/28 13:36
S63	21805	S61 and S62	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/04/28 13:36
S64	3	US "20050155790"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/04/28 15:59
S65	3	"20050155790"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/04/28 16:00
S66	6	("6774497").URPN.	USPAT	ADJ	ON	2009/10/16 15:42
S67	1	"6560122".PN.	USPAT; USOCR	ADJ	ON	2009/10/16 15:44
S68	1	"6365441".PN.	USPAT; USOCR	ADJ	ON	2009/10/16 16:07
S69	1	"6294840".PN.	USPAT; USOCR	ADJ	ON	2009/10/16 16:07
S70	1	"6271107".PN.	USPAT; USOCR	ADJ	ON	2009/10/16 16:07
S71	1	"6265776".PN.	USPAT; USOCR	ADJ	ON	2009/10/16 16:08
S72	1	"6228678".PN.	USPAT; USOCR	ADJ	ON	2009/10/16 16:08
S73	1	"6190940".PN.	USPAT; USOCR	ADJ	ON	2009/10/16 16:09
S74	1	"6121689".PN.	USPAT; USOCR	ADJ	ON	2009/10/16 16:29
S75	1	"5925936".PN.	USPAT; USOCR	ADJ	ON	2009/10/16 16:29
S76	34	("6190940").URPN.	USPAT	ADJ	ON	2009/10/16 16:30
S77	706994	(PCB or (printed circuit board) or PWB or (printed wiring board) or (circuit board) or (wiring board))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/16 16:53

S78	1165943	((IC or Chip or semiconductor) same (electrode or pad or terminal or contact))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/16 16:54
S79	2578456	(bump or ball or stud or post)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/16 16:55
S80	52864	S77 and S78 and S79	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/16 16:55
S81	542	((underfill or (underfill near2 resin)) same ((solder resist) or resist))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/16 16:56
S82	2512	((underfill or (underfill near2 resin)) and ((solder resist) or resist))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/16 16:56
S83	1470	S80 and S82	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/16 16:56
S84	493	volume and S83	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/16 16:56
S85	242	S84 and @ad<="20040329"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/16 17:00
S86	213	S81 and @ad<="20040329"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/16 17:36
S88	5718	(solder resist) same (aperture or hole or gap or void or open or opening)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/16 18:14
S89	1933	S80 and S88	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/16 18:14

S90	311	S82 and S89	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/16 18:15
S91	96	S90 and @ad<="20040329"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/16 18:15
S92	645	S83 and @ad<="20040329"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/16 18:29
S93	549	S92 not S91	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/16 18:29
S94	549	S93 not S90	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/16 18:29
S95	1	"10594844"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/17 14:26
S96	34	("6190940").URPN.	USPAT	ADJ	ON	2009/10/17 14:29
S97	0	("2002/0033525").URPN.	USPAT	ADJ	ON	2009/10/17 14:40
S98	2643	257/778.ccls.	USPAT	ADJ	ON	2009/10/17 14:45
S99	904	257/779.ccls.	USPAT	ADJ	ON	2009/10/17 14:45
S100	1404	257/780.ccls.	USPAT	ADJ	ON	2009/10/17 14:45
S101	4004	S98 or S99 or S100	USPAT	ADJ	ON	2009/10/17 14:45
S102	361	S101 and (solder resist)	USPAT	ADJ	ON	2009/10/17 14:48
S103	258	S102 and @ad<="20040329"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/17 14:49

S104	1031	(pitch or width) same (solder resist)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/17 14:50
S105	39	S104 and S101	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/17 14:50
S106	21	("6049122").URPN.	USPAT	ADJ	ON	2009/10/17 14:57
S107	1	"6049122".PN.	USPAT; USOCR	ADJ	ON	2009/10/17 15:01
S108	1	"5650595".PN.	USPAT; USOCR	ADJ	ON	2009/10/17 15:01
S109	1	"5397864".PN.	USPAT; USOCR	ADJ	ON	2009/10/17 15:01
S110	1	"5397864".PN.	USPAT; USOCR	ADJ	ON	2009/10/17 15:01
S111	1	"5218234".PN.	USPAT; USOCR	ADJ	ON	2009/10/17 15:01
S112	1	"4859808".PN.	USPAT; USOCR	ADJ	ON	2009/10/17 15:01
S113	1	"10644487"	USPAT	ADJ	ON	2009/10/17 15:12
S114	2	"10644487"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/17 15:12
S115	0	("2005/0155790").URPN.	USPAT	ADJ	ON	2009/10/17 15:12
S116	1	"6049122".PN.	USPAT; USOCR	ADJ	ON	2009/10/17 15:24
S117	21	("6049122").URPN.	USPAT	ADJ	ON	2009/10/17 15:24
S118	208	aperture volume	USPAT	ADJ	ON	2009/10/17 15:25
S119	0	S101 and S118	USPAT	ADJ	ON	2009/10/17 15:25
S120	23729	aperture same volume	USPAT	ADJ	ON	2009/10/17 15:25
S121	15	S101 and S120	USPAT	ADJ	ON	2009/10/17 15:26
S122	1	"6049122".PN.	USPAT; USOCR	ADJ	ON	2009/10/17 15:28

S123	2507	(solder (ball or bump)) same volume	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/17 15:43
S124	23729	aperture same volume	USPAT	ADJ	ON	2009/10/17 15:43
S125	71	S123 and S124	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/17 15:43
S126	46	S123 same S124	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/17 15:44
S127	59	("5658827").URPN.	USPAT	ADJ	ON	2009/10/17 15:47
S128	6517	(solder (ball or bump)) same (radius or diameter)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/17 16:01
S129	42	S124 and S128	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/17 16:01
S130	13213	(solder (ball or bump or globe)) same (radius or diameter or volume or width or height)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/17 16:05
S131	512788	(hole or aperture or opening or gap or void) same (volume or width or height)	USPAT	ADJ	ON	2009/10/17 16:06
S132	2521	S130 and S131	USPAT	ADJ	ON	2009/10/17 16:06
S133	1380	S130 same S131	USPAT	ADJ	ON	2009/10/17 16:06
S134	1091	S133 and @ad<="20040329"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/17 16:06
S135	125	S134 and (solder resist)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/17 16:07

S136	185	(hemisphere or hemispherical) near2 (solder bump)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM TDB	ADJ	ON	2009/10/17 16:11
S137	3407	257/e21.511.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM TDB	ADJ	ON	2009/10/17 16:29

EAST Search History (Interference)

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